

POTTING COMPOUND, EPOXY  
Bisphenol A-Type  
Filled, Room Temperature Cure, Low Exotherm

1. SCOPE:

1.1 Form: This specification covers a filled, room-temperature-polymerizing epoxy resin formulation, supplied as a two-component system.

1.2 Application: Primarily for use as a potting or sealing material where a low coefficient of thermal expansion is desired.

2. APPLICABLE DOCUMENTS: Shall be as shown in AMS 3731.

3. TECHNICAL REQUIREMENTS:

3.1 Basic Specification: The complete requirements for procuring the product described herein shall consist of this document and the latest issue of the basic specification, AMS 3731.

3.2 Material: Shall be an epoxy-based polymer with a filler and a curing agent.

3.3 Properties: The compound shall conform to the following requirements:

3.3.1 Mixed Uncured Compound: The compound, mixed in accordance with manufacturer's instructions, shall exhibit the following properties:

3.3.1.1 Viscosity: Shall be not greater than 10,000 centipoise (10.0 Pa s) at 23°C (73°F), determined within 5 min. after mixing, using a Brookfield Model LVF viscometer and No. 3 spindle at 6 revolutions per minute.

3.3.1.2 Pot Life: Usable life of the compound, defined as the time to attain double the initial viscosity determined in 3.3.1.1, shall be not less than 45 min. at 23°C (73°F).

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3.3.1.3 Curing Time: The time required to develop the cured product properties specified in 3.3.2 shall be not more than 5 days at 23°C (73°F) or not more than 4 hr at 95°C (200°F).

3.3.1.4 Demold Time: The time required before the part can be removed from the mold and retain its integrity shall be not more than 24 hr at 23°C (73°F).

3.3.2 Cured Product: The compound, mixed and cured in accordance with manufacturer's instructions, shall exhibit the following properties, determined in accordance with test methods listed in AMS 3731:

3.3.2.1	Flexural Strength, min	11,500 psi (80 MPa)
3.3.2.2	Izod Impact Strength, per unit of notch, min	0.3 ft-lb per in. (16 J/m)
3.3.2.3	Compressive Strength, min	18,000 psi (125 MPa)
3.3.2.4	Insulation Resistance	
3.3.2.4.1	At 23°C (73°F), min	1x10 <sup>6</sup> megohms
3.3.2.4.2	At 121°C (250°F), min	1x10 <sup>3</sup> megohms
3.3.2.4.3	After hydrolytic stability conditioning, min	1x10 <sup>4</sup> megohms
3.3.2.5	Dielectric Constant at 1 KHz, max	5.5
3.3.2.6	Dissipation Factor at 1 KHz, max	0.04
3.3.2.7	Heat Deflection Temperature at 264 psi (1.8 MPa), min	74°C (165°F)
3.3.2.8	Coefficient of Linear Thermal Expansion, max	
3.3.2.8.1	From -54°C to +23°C (-65°F to +73°F)	35x10 <sup>-6</sup> (mm/mm)/deg C (20x10 <sup>-6</sup> in. per in. per deg F)
3.3.2.8.2	From 23°C to 74°C (73°F to 165°F)	45x10 <sup>-6</sup> (mm/mm)/deg C (25x10 <sup>-6</sup> in. per in. per deg F)
3.3.2.9	Water Absorption after 24 hr Immersion, max	0.25%